

(1.00 mm) .0394"

PCIE-LP SERIES

PCI EXPRESS® LOW-PROFILE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?PCIE-LP

Insulator Material:
LCP

Contact:
Phosphor Bronze

Plating:
Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:
2.1 A per pin

(2 adjacent pins powered)

Operating Temp:
-55 °C to +125 °C

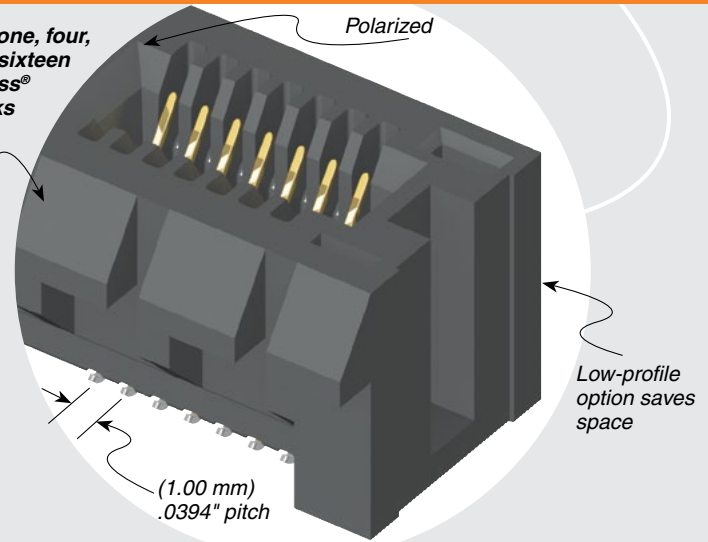
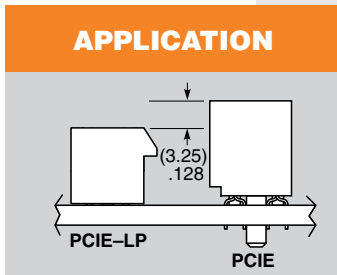
PROCESSING

Lead-Free Solderable:
Yes

Card Mates:
(1.60 mm) .062" card

Cable Mates:
PCIEC

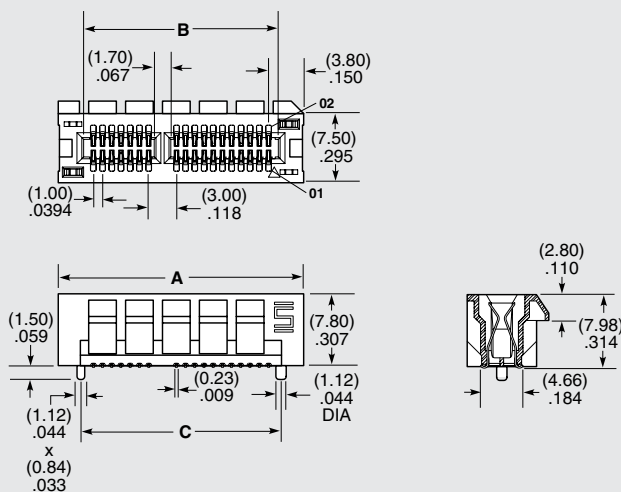
Supports one, four, eight and sixteen PCI Express® GEN 4 links



PCIE	LP	NO. OF LANES	01	PLATING OPTION	DV	A	OPTION	PACKAGING
-01, -04, -08, -16				-F = Gold flash on contact, Matte Tin on tai	-S = 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail	-WT = Weld Tab	-K = Polyimide film Pick & Place Pad	-TR = Tape & Reel (Available with -01, -04 -08 lanes only)

OTHER SOLUTIONS

- Press-fit tails in development



NO. OF LANES	A	B	C
-01	(26.60) 1.047	(21.00) .827	(21.70) .854
-04	(40.60) 1.598	(35.00) 1.378	(35.70) 1.406
-08	(57.60) 2.268	(52.00) 2.047	(52.70) 2.075
-16	(90.60) 3.567	(85.00) 3.346	(85.70) 3.374

PCIE-LP-01-01-X-DV-A SHOWN

PCI-SIG®, PCI Express® and the PCIe® design marks are registered trademarks and/or service marks of PCI-SIG.

Note:
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.